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Docket No. AMENDMENT TRANSMITTAL LETTER TESSERA 3.0-196 DIV Application No. Filing Date Examiner Art Unit L. A. Gurley 10/685,361 October 14, 2003 2812 Applicant(s): John W. Smith and Belgacem Haba Invention: SEMICONDUCTOR CHIP PACKAGE WITH INTERCONNECT STRUCTURE TO THE COMMISSIONER FOR PATENTS Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below. **CLAIMS AS AMENDED** Claims Highest Number Remaining Number **Extra Claims** Previously After <u>Ame</u>ndment Present Rate Paid **Total Claims** 25 27 х Independent 2 3 х Claims Multiple Dependent Claims (check if applicable) Other fee (please specify): Extension for response within third month TOTAL ADDITIONAL FEE FOR THIS AMENDMENT: Small Entity x Large Entity x No additional fee is required for this amendment. × Please charge Deposit Account No. 12-1095 in the amount of \$ A duplicate copy of this sheet is enclosed. A check in the amount of \$ to cover the filing fee is enclosed. Payment by credit card. Form PTO-2038 is attached. 12-1095 x The Director is hereby authorized to charge and credit Deposit Account No. as described below. A duplicate copy of this sheet is enclosed. x Credit any overpayment. Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17. Dated: December 22, 2004 Marcus J. Millet Attorney Reg. No.: 28,241 LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP 600 South Avenue West Westfield, New Jersey 07090 (908) 654-5000

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date shown below.

Dated: December 22, 2004

Signature:

_ (Marcus J. Millet)